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(54) **SEMICONDUCTOR DEVICE**

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ABSTRACT (57)

Provided is a semiconductor device with improved moisture resistance. A semiconductor device includes a semiconductor chip, a case, a sealing material arranged in the case and sealing the semiconductor chip, and a lid in close contact with the sealing material, wherein the case has at least one projection, the lid is provided with at least one first hole, and the at least one projection is in the at least one first hole, respectively, whereby the lid is fixed to the case.

101

